

ABSTRACT OF THE DISCLOSURE

An epoxy resin composition for encapsulating semiconductors including (A) an epoxy resin, (B) a phenol resin, (C) an inorganic filler, (D) a curing promoter, and (E) a surface-treated coloring agent, wherein the coloring agent before the surface treatment is a carbon precursor with a carbon content of 90 wt% or more or carbon black having a DBP absorption of $100 \text{ cm}^3/100 \text{ g}$ or more, and a semiconductor device encapsulated with the epoxy resin composition. The epoxy resin composition can produce semiconductors which are free from electrical failures such as a short circuit, a leak current, and the like, do not induce wire deformation, and exhibits excellent laser marking characteristics.